What is claimed is:

1. A method comprising:

   a) providing a dielectric substrate;

   b) treating a surface of the dielectric substrate by applying a solution comprising one or more curable amine compounds and one or more curable epoxy compounds adjacent the surface of the dielectric substrate, the amount of the one or more curable amine compounds to the one or more curable epoxy compounds in the solution is included in the solution in excess of the one or more curable epoxy compounds;

   c) drying the solution adjacent to the treated surface of the dielectric substrate;

   d) electrolessly plating a metal on the treated surface of the dielectric substrate; and

   e) heating the metal plated dielectric substrate to cure the one or more amine compounds and the one or more epoxy compounds.

2. The method of claim 1, further comprising selectively electroplating a metal layer on the electrolessly plated metal prior to step e).

3. The method of claim 1, further comprising applying a promoter to the treated surface of the dielectric followed by applying a neutralizer to the treated surface of the dielectric followed by conditioning the treated surface of the dielectric followed by applying a pre-dip to the treated surface of the dielectric and then applying a catalyst to the treated dielectric surface after c) and prior to d).

4. The method of claim 1, wherein a weight ratio of the one or more curable amine compounds to the one or more epoxy compounds is at least 2:1.

5. The method of claim 4, wherein the weight ratio of the one or more curable amine compounds to the one or more epoxy compounds is from 2:1 to 4;1.

6. The method of claim 1, wherein the solution further comprises one or more surfactants.

7. The method of claim 1, wherein the solution comprises one or more curing accelerators.

8. The method of claim 1, wherein the one or more curable amine compounds are polyamine compounds chosen from aliphatic, cycloaliphatic, araliphatic and aromatic polyamines.

9. The method of claim 1, wherein the one or more curable epoxy compounds are chosen from glycidyl ethers, glycidyl esters, polyfunctional di- and triglycidyl ethers, bisphenol based epoxies and Novolac epoxy compounds.

10. The method of claim 1, wherein the dielectric substrate comprises a polymer resin chosen from epoxy resins, acrylonitrilebutadienestyrene, polycarbonates, polyphenylene oxides, polyphenylene ethers, polyphenylene sulfides, polysulfones, polyamides, polyesters, polybutyleneterephthalate, polyetheretherketones, liquid crystal polymers, polyurethanes, polyetherimides, polytetrafluoroethylene, polytetrafluoroethylene blends, cyanate esters and composites thereof.

1. A method comprising:

a) providing a dielectric substrate;

b) treating a surface of the dielectric substrate by applying a solution comprising one or more curable amine compounds and one or more curable epoxy compounds adjacent the surface of the dielectric substrate, the amount of the one or more curable amine compounds to the one or more curable epoxy compounds in the solution is at a weight ratio of at least 2:1;

c) drying the solution adjacent to the treated surface of the dielectric substrate;

d) electrolessly plating a metal on the treated surface of the dielectric substrate; and

e) heating the metal plated dielectric substrate to cure the one or more amine compounds and the one or more epoxy compounds.

2. The method of claim 1, further comprising selectively electroplating a metal layer on the electrolessly plated metal prior to step e).

3. The method of claim 1, further comprising applying a promoter to the treated surface of the dielectric followed by applying a neutralizer to the treated surface of the dielectric followed by conditioning the treated surface of the dielectric followed by applying a pre-dip to the treated surface of the dielectric and then applying a catalyst to the treated dielectric surface after c) and prior to d).

4. The method of claim 1, wherein the weight ratio of the one or more curable amine compounds to the one or more epoxy compounds is from 2:1 to 4:1.

5. The method of claim 1, wherein the solution further comprises one or more surfactants.

6. The method of claim 1, wherein the solution comprises one or more curing accelerators.

7. The method of claim 1, wherein the one or more curable amine compounds are polyamine compounds chosen from aliphatic, cycloaliphatic, araliphatic and aromatic polyamines.

8. The method of claim 1, wherein the one or more curable epoxy compounds are chosen from glycidyl ethers, glycidyl esters, polyfunctional di- and triglycidyl ethers, bisphenol based epoxies and Novolac epoxy compounds.

9. The method of claim 1, wherein the dielectric substrate comprises a polymer resin chosen from epoxy resins, acrylonitrilebutadienestyrene, polycarbonates, polyphenylene oxides, polyphenylene ethers, polyphenylene sulfides, polysulfones, polyamides, polyesters, polybutyleneterephthalate, polyetheretherketones, liquid crystal polymers, polyurethanes, polyetherimides, polytetrafluoroethylene, polytetrafluoroethylene blends, cyanate esters and composites thereof.